

3.2x1.6mm SMD CHIP LED LAMP

### **Features**

- $\bullet 3.2 mmx 1.6 mm$  SMT LED, 1.1 mm THICKNESS.
- •LOW POWER CONSUMPTION.
- •WIDE VIEWING ANGLE.
- •IDEAL FOR BACKLIGHT AND INDICATOR.
- •VARIOUS COLORS AND LENS TYPES AVAILABLE.
- $\bullet PACKAGE: 2000PCS \ / \ REEL.$
- •MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- •Rohs Compliant.

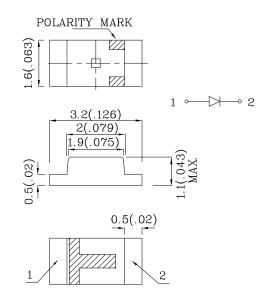




#### Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm$  0.2(0.008") unless otherwise noted.
- $3. {\rm Specifications}$  are subject to change without notice.

Absolute Maximum Ratings (Ta=25°C)		MDK (InGaAlP)	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	185	mA
Power Dissipation	Рт	75	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	-0



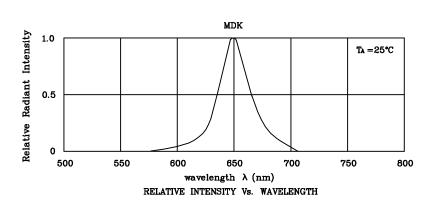
Operating Characteristic (TA=25°C)	MDK (InGaAlP)	Unit	
Forward Voltage (Typ.) (IF=20mA)	$V_{\mathrm{F}}$	1.95	V
Forward Voltage (Max.) (IF=20mA)	$V_{\mathrm{F}}$	2.5	V
Reverse Current (Max.) (VR=5V)	IR	10	uA
Wavelength of Peak Emission (Typ.) (IF=20mA)	λΡ	650	nm
Wavelength of Dominant Emission (Typ.) (IF=20mA)	λ D	635	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	Δλ	28	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	С	35	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λ P	Viewing Angle 2 0 1/2
				min.	typ.		
XZMDK55W	Red	InGaAlP	Water Clear	50	148	650	120°
Published Date :	JAN 23, 2008	Drawi	ng No :XDSA1297	V5	Chec	ked : B.L.LIU	P.1/4

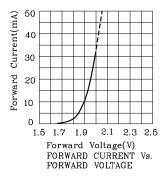


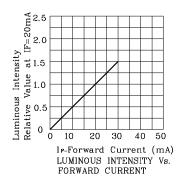
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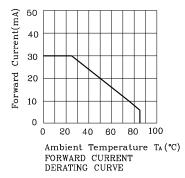


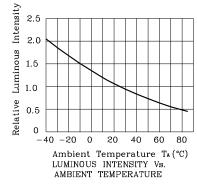


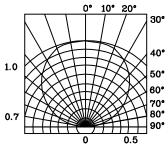
## **❖** MDK









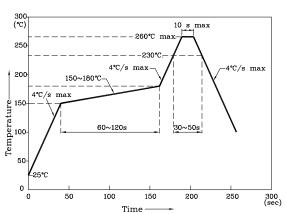


SPATIAL DISTRIBUTION



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Reflow Soldering Profile For Lead-free SMT Process.



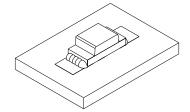
NOTES:

- 1. Maximum soldering temperature should not exceed 260°c.
- 2. Recommended reflow temperature: 145°c-260°c.
- 3. Do not put stress to the epoxy resin during high temperatures conditions.

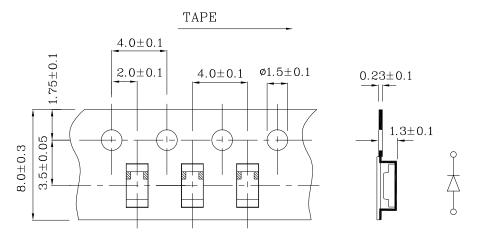
# ❖ Recommended Soldering Pattern (Units: mm;Tolerance:± 0.1)

**❖** The device has a single mounting surface. The device must be mounted according to the specifications.





\* Tape Specification (Units:mm)



#### Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage:  $\pm$ -0.1V

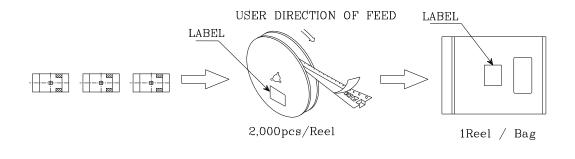
Note: Accuracy may depend on the sorting parameters.  $\,$ 

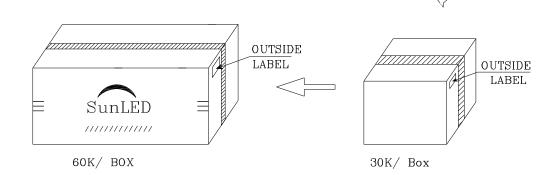


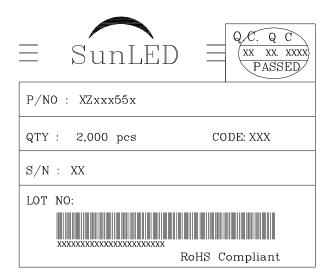
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## PACKING & LABEL SPECIFICATIONS

## XZMDK55W







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